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User Guide for the GLAST BFEM Tracker

W. Kröger and M. Hirayama
Santa Cruz Institute for Particle Physics
University of California, Santa Cruz

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Abstract

The GLAST Balloon-Flight Engineering Model (BFEM) tracker is the Beam-Test Engineering Model (BTEM) tracker modified for the balloon flight in 2001. This document describes hardware components of the tracker, beam test setup, tracker operation, and readout scheme. Detailed information of the tracker operations is also provided in later sections.

Contents

1	How to Read This User Guide	2
2	Pre-Flight Setup	3
3	BFEM Tracker	5
3.1	Detector Layer	5
3.2	Tray Stack and Tracker Coordinate	6
3.3	Readout Electronics	6
4	Tracker Operation	9
4.1	Readout Procedure	9
4.2	Tracker Configuration	10
4.3	Addressing Scheme	12
5	Configuration	14
5.1	Controller and Cable Addresses	14
5.2	Known Problems	16
6	Testing	17
6.1	Strip Maps	17
6.2	Cosmic Particles	17
7	Details on Tracker	18
7.1	Control Register	18
7.2	GTFE Command	19
7.3	GTRC Command	20
7.4	Resetting Chips	20
7.5	Readout Cable and Repeater Board	22

1 How to Read This User Guide

This document consists of three parts. First, a tracker part of the pre-flight setup is shown in section 2. Then, sections 3 and 4 briefly describes tracker hardware components, tracker operation, and readout scheme. These sections are of interest for everyone that has to interact with the tracker. And finally, section 7 describes more detailed information of tracker operation. The section can be a reference for tracker experts.

It is not necessary for everyone to read through all of this document. The part of the document you should read depends on what extent you are operating the tracker to. From that point of view, there are three different types of tracker users: operators, workers, and experts.

Operators are responsible to ensure that the tracker is running properly during pre-flight or in-flight operation. They are recommended to read section 2. Sections 3 and 4 are interesting for better understanding of the tracker.

Workers monitor the data, calibrate the tracker, and modify the tracker configuration depending on the tracker status. They are required to understand all the subjects covered by this document. They will find the software configuration of the tracker and a few typical testing methods in sections 5 and 6.

Experts take a lead in setting up the tracker, changing the setup, planning and revising a run plan. Section 7 will be references for experts.

2 Pre-Flight Setup

The tracker is controlled by a TKR TEM board in a VME crate called TKR VME (Figure 1). Eight shielded cables connect the TEM board to tracker readout electronics through eight repeater boards. The repeater board is a small printed-circuit board attached to the base plate of the tracker, to buffer signals from the tracker and to filter the power supply lines (See section 3 for more explanations). All the electrical connection for the tracker, such as power lines and signal lines, are on those eight cables.

Detector bias and power for readout electronics are supplied by the Tracker Power Supply connected to the TEM board. It converts 28 V input into all the power lines that the Tracker Tower needs: detector bias, DVDD (digital power), AVDD (analog power), and AVDD2 (2nd analog power). The repeater boards are powered from the digital power DVDD. The TKR VME crate also includes a CPU board with an Ethernet port. On the CPU board, VxWorks is running as an operating system to control and access the TKR TEM board. The VxWorks system is controlled through the Ethernet connection.

Before applying detector bias, check the compliance level. Start with relatively low voltage like 2 V, slowly raise the voltage with watching detector current every time you raise the voltage. To be safe, raise the bias with 1 V step up to 10 V and with 10 V step afterwards. You might see detector current reach compliance level when you raise the voltage. You should wait for a couple of seconds until detector current gets down below compliance level before raising it to the next voltage level.

Here is a list of instruments for the tracker part of the setup below. Also, setting of power supplies are shown in Table 1 with typical currents listed.

Tracker Described in section 3.

TKR VME VME crate including a TKR TEM board and a CPU board with an Ethernet access to control the TEM board. A local monitor will be attached for booting the system.

Tracker Power Supply DC to DC converter to supply detector bias, digital power (DVDD), analog power (AVDD), and the 2nd analog power (AVDD2). The input voltage is 28 V. Repeater boards are powered from the digital power (DVDD).

Table 1. Power Consumption of Tracker Power Supply

	Voltage ^{a)}		Typical Current
	@ Power supply	@ Repeater board	
Input	+28 V	—	0.7 A
Detector Bias	+100 V	—	100–170 μ A
DVDD	+3.3 V	\approx 3.0 V	1.4 A
AVDD2	+3.3 V	\approx 2.0 V	0.94 A
AVDD	+5.2 V	\approx 5.0 V	0.7 A

a) The voltages drop along the cables due to currents of \approx 1 A on DVDD, AVDD, and AVDD2.

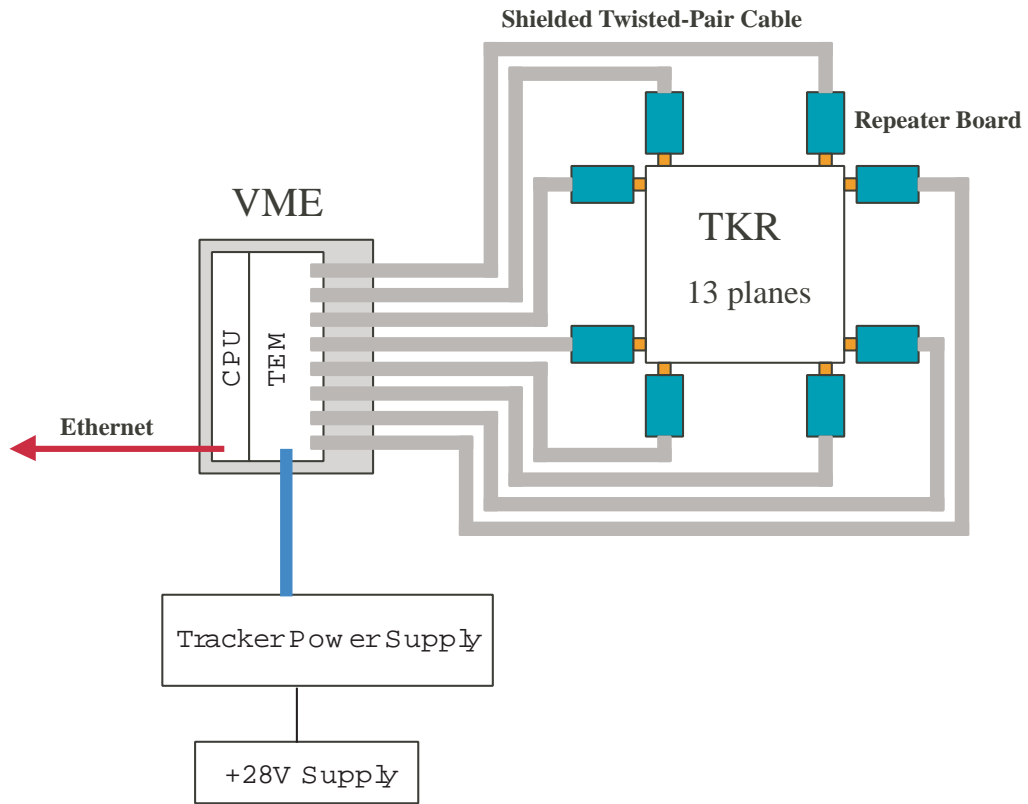


Fig. 1. Schematic drawing of pre-flight setup for the BFEM tracker

3 BFEM Tracker

In this section, the tracker hardware configuration is described. The beam test tracker consists of 14 detector trays stacked on top of each other. On each tray silicon strip detectors, lead sheets for pair conversion, and readout electronics are mounted. The trays are electrically interconnected with 8 Kapton cables attached on 4 sides of the tracker, which connects all the electronics to a tower controller. Below in this section, each component is described in more detail.

3.1 Detector Layer

Silicon strip detectors are mounted on the top and the bottom side of a detector tray. A set of detectors on one side of a tray forms a detector layer measuring X or Y of a track. An x-y plane is formed between two trays when one is stacked on the other; a top layer of the lower tray and a bottom layer of the upper tray forms an x-y plane. Of the 14 trays, the top-most tray carries detectors only on its bottom side, and the bottom-most tray only on its top side. Detectors are mounted on the both side on the rest of fifteen trays. In the beam test tracker there are 26 layers which form 13 x-y planes, in total.

A silicon detector layer consists of 3, 4, or 5 detector ladders depending on the location of the layer, where a detector ladder consists either of five 4-inch detectors or of three 6-inch detectors glued and wire-bonded together. A 4-inch detector is a square strip detector of 6.4 cm by 6.4 cm with 320 p^+ strips at 195 μm pitch, and a 6-inch one is rectangle, 6.4 cm wide and 10.68 cm long, with the same number of strips with the same pitch as a 4-inch detector. This was designed so that both of five 4-inch detectors and three 6-inch detectors form a detector ladder 6.4 cm wide and 32 cm long. And five detector ladders will cover a square region of 32 cm by 32 cm with 1600 strips. In the tracker 112 ladders are used in total; 32 ladders of them are of 4-inch detectors (160 detectors) and 80 of 6-inch detectors (240 detectors).

Of the 13 x-y planes 5 planes from the top of the tracker are only partially covered by detectors; the top 4 planes consist of three ladders on each of X- and Y-measuring layer (3×3 plane) and the 5th plane from the top of the tracker consists of four ladders on each (4×4 plane). The rest of 8 planes are fully covered, namely, five ladders are on both layers (5×5 plane).

Also, on the upstream side of each x-y plane there is a lead converter. There are three different thicknesses, 3.5 % radiation length (normal thickness), 25 % radiation length (called "super GLAST"), and 0 % radiation length (or no lead sheet). The 3.5 % lead sheets are placed on the top 8 planes and the 25 % lead sheets are on the 9th, 10th, and 11th planes. There is no lead sheet placed in front of the bottom two planes.

3.2 Tray Stack and Tracker Coordinate

The 14 trays are stacked up with every 2nd tray rotated by 90 degree to form an x-y plane between trays. The bottom-most tray is bolted to a base plate of the tracker and the orientation of the bottom-most tray in reference to the base plate is unique. The 2nd tray from the bottom is rotated by 90 degree clockwise in reference to the bottom-most tray. The 3rd tray is stacked in the same orientation as the bottom-most tray, the 4th tray is in the same orientation as the 2nd tray, and so on. This gives you the top-most tray being placed in different orientation as the bottom-most tray.

On each tray X or Y of a track is measured. A layer on the bottom-most tray is measuring Y. Both layers on the 2nd tray from the bottom then measure X. Layers on the 3rd tray measure Y, ones on the 4th X, and so on. This gives you a layer on the top-most tray measuring X. The X- or Y-coordinate increases from the left side towards the right side on a tray, where a left side of the tray is defined as the left side when you look at the top side of the tray with a readout electronics for a top side layer set at the bottom of your view. The left-most strip always has a strip number 0 on both sides of a tray, no matter which axis it measures. A strip number ranges from 0 to 1599 on a full tray, from 0 to 1279 on a 4×4 tray, and from 0 to 959 on a 3×3 tray.

The Z-axis of the tracker is defined as an axis going from the bottom to the top of the tracker. The plane number is assigned to each x-y plane starting with 0 increasing in +Z direction.

Table 2 summarizes the detector configuration of the tracker. Figure 2 shows the tray stack and the tracker coordinate system. The figure also shows detector coverage of each x-y plane and the converter thickness.

3.3 Readout Electronics

Each silicon layer is read out by a high density interface (HDI), which is a printed circuit board with 25 front-end chips (GTFE64), two controller chips (GTRC), and passive components mounted. Two HDI's are attached on two sides of a tray, one on a side to read out a layer on the top side of the tray and the other on the opposite side to read out one on the bottom. The top-most and the bottom-most tray has only one HDI attached, since detectors are mounted only on one side of the tray. There are 26 HDI's in total with 52 controller chips and 650 front-end chips.

Each front-end chip reads out 64 strips, which covers 1600 strips with 25 chips on an HDI. Hit information of the 1600 strips is recorded for every trigger and kept in 8-deep data buffers of the front-end chips until it is read out. The data is read out by one of the controller chips. During readout, a front-end chip sends out the data to a neighboring chip, either on the right or on the left, and the

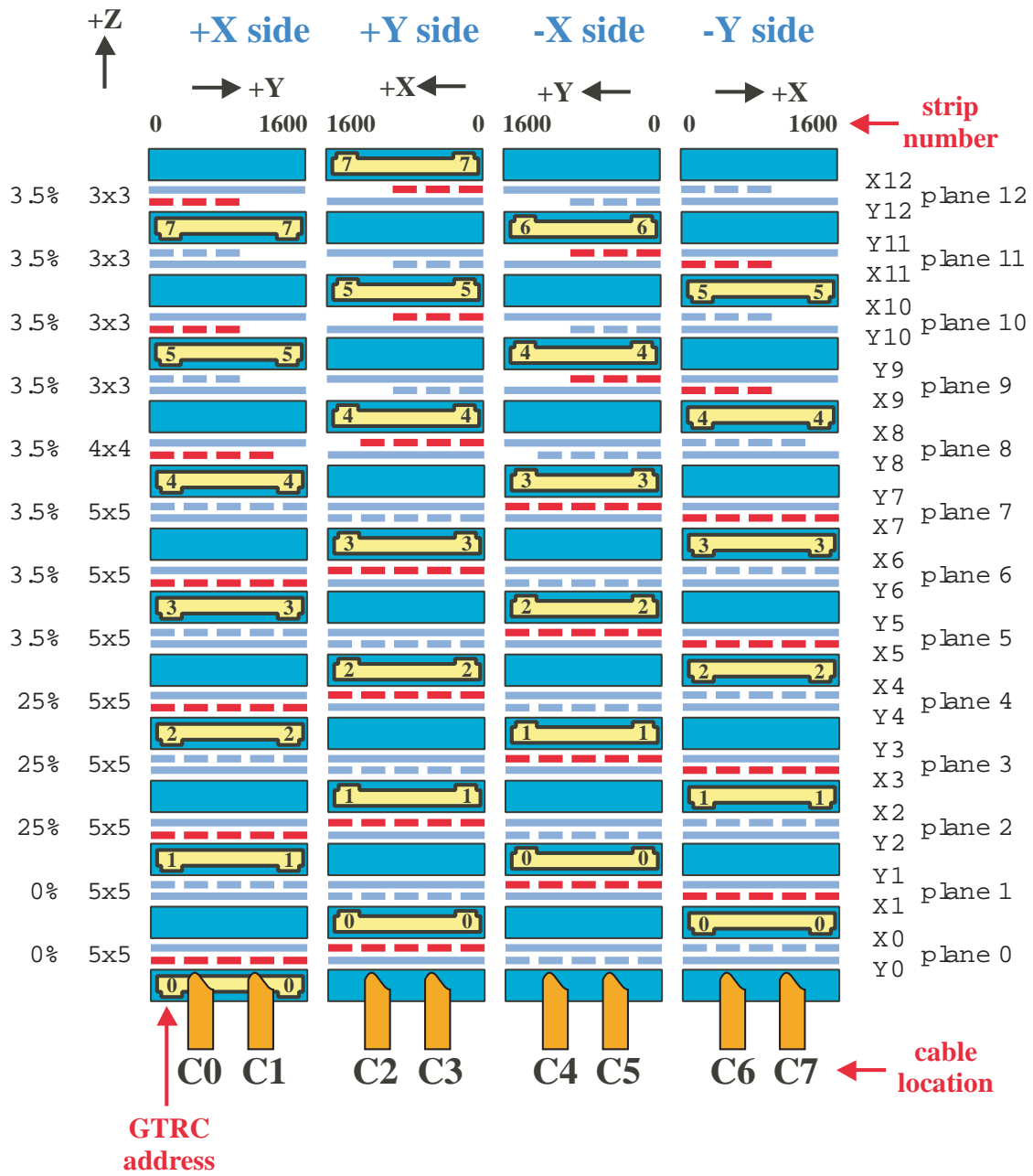


Fig. 2. Schematic drawing of the BFEM tracker tower.

Table 2. Summary of 13 x-y planes of the tracker

	Pb thickness	Active strip # in layer ^{a)}	
		Top layer	Bottom layer
Plane 12	3.5 % R.L.	0-959 (X)	0-959 (Y)
Plane 11	3.5 % R.L.	0-959 (Y)	0-959 (X)
Plane 10	3.5 % R.L.	0-959 (X)	0-959 (Y)
Plane 9	3.5 % R.L.	0-959 (Y)	0-959 (X)
Plane 8	3.5 % R.L.	0-1279 (X)	0-1279 (Y)
Plane 7	3.5 % R.L.	0-1599 (Y)	0-1599 (X)
Plane 6	3.5 % R.L.	0-1599 (X)	0-1599 (Y)
Plane 5	3.5 % R.L.	0-1599 (Y)	0-1599 (X)
Plane 4	25 % R.L.	0-1599 (X)	0-1599 (Y)
Plane 3	25 % R.L.	0-1599 (Y)	0-1599 (X)
Plane 2	25 % R.L.	0-1599 (X)	0-1599 (Y)
Plane 1	0 % R.L.	0-1599 (Y)	0-1599 (X)
Plane 0	0 % R.L.	0-1599 (X)	0-1599 (Y)

a) Measuring axis in parentheses

neighbor passes it to the next neighbor. Readout direction can be set by command to individual front-end chip. The hit data is transferred in this manner all the way through the HDI until the last chip passes it to one of the controller chips.

Two controller chips on an HDI control all front-end chips on the HDI. One chip locates on the left side of an HDI and reads out left-going data, while the other on the right and reads out right-going data. Both of the controller chips can read out either the entire side of the tray or a part of it. Arbitrary number of front-end chips can be assigned to be read out from the left side or the right side of an HDI.

A controller chip is also an interface to a tower electronics module (TEM). It receives commands from a TEM board and sends out hit information to a TEM board after it reads out front-end chips and converts data format. These communication are made through a Kapton flexible cable connecting HDI's to a TEM board through a repeater board which buffers weak signals from HDI's. There are 8 HDI's on each of four sides of the tracker. A set of 8 HDI's is daisy-chained and connected to a TEM board with a Kapton cable. The left side controller chip and the right side one are connected independently, there are 8 cables connected to the TEM board in total.

4 Tracker Operation

The tracker is operated through a TEM board on a VME crate called TKR VME. The tracker can be configured, operated, and readout with the TKR VME system through Ethernet. In response to an event trigger or upon our request sent through Ethernet, the TEM board sends out commands to controller chips on HDI's and reads their responses. The responses include hit information during normal operation. The TEM board interprets the hit information, reformat them, and put them into an event FIFO, which is visible in a VME memory space.

In sections below, tracker readout procedure is briefly explained. Also, a control register of a front-end chip, that of a controller chip, and addressing scheme for both chips are described.

4.1 Readout Procedure

To operate the tracker, all the HDI's must be configured at first. All control parameters, such as threshold, must be set by writing them into a control register of a front-end chip or that of a controller chip. Contents of control registers are described in a later section.

Once it is configured, the tracker is ready to trigger a DAQ system in response to a particle passing through the tracker. If the amount of charges collected by a strip exceeds threshold, a corresponding channel of a front-end chip issues a fast-OR signal, which is immediately sent to a TEM board. At the same time, the length of the fast-OR signal, called Time-over-Threshold (ToT), is measured by a controller chip in charge of the front-end chip.

The TEM board judges whether to read it out or not. If the TEM board sees a hit (or more) on three consecutive x-y planes, the event should be read out ("3-in-a-row" condition). If and only if the TEM board receives trigger signals from three neighboring planes, it requests a level 1 trigger (L1T) to the DAQ system by sending an L1T request signal. In response to an L1T request, the DAQ system sends out an L1T signal to the TKR TEM board and other TEM boards for other instruments. The TKR TEM board fans out the L1T signal to all the layers in the tracker (trigger acknowledge signal), with which all the front-end chips latch hit status of all the 64 channels and store it to an event FIFO.

The TEM board starts a readout sequence. The TEM board sends a Read-Event command to all the controller chips on the tracker. In response to the command, controller chips automatically issue a Read-Event command to all the front-end chips on their HDI. The front-end chips responds it by extracting the hit status from an event FIFO and shifting it out all the way across the HDI until it gets to a controller chip. A controller chip counts a strip number while it is receiving hit status from front-end chips, and store the strip number into an event

buffer when it is a hit on the channel. A controller chip also stores the time-over-threshold, the number of hits, a frame check sequence, etc., in the event buffer. To discard an event, the TEM board sends a Clear-Event command to all the controller chips, which issues a Clear-Event command to all the front-end chips. The front-end chips will erase the event in FIFO.

For an event to be read out, a TEM board issues a readout token, which is a digital signal given to a controller chip on the lowest layer on a cable. When a controller chip receives a token, it sends out contents of an event buffer to a controller chip on a lower neighboring layer, or to a TEM board in case of the lowest layer, and passes a token to a higher neighboring layer. Through this daisy chain of token/data passing, a TEM board eventually receives all the event buffer contents of eight controller chips on a readout cable one after another, as a readout token is being passed from the bottom controller chip to the top one. Readout procedures on all the eight readout cables takes place simultaneously. A TEM board put them altogether into an event buffer on the board, which can be read out through Ethernet.

Readout sequence for an event can be started anytime after the event, even after another event occurs. However, there is a limitation on the number of events which the tracker can hold until they are readout. A front-end chip can hold eight events and a controller chip has two event buffer. Once the number of events exceed those limits, the oldest event will be lost and overwritten by the new event. It is a TEM board's responsibility to keep track the number of events in front-end chips and in controller chips.

4.2 Tracker Configuration

A front-end chip and a controller chip have its own control register in it to store configuration of a tracker. Contents of control registers of a front-end chip can be re-written by a TEM board at anytime by sending a set-register command to the HDI's.

A front-end chip holds following information in the control register of 207 bits in total. To set a set of parameters to a front-end chip, a TEM board should send a Load-GTFE-Register command to a controller chip on the same HDI as the front-end chip, and let it send a Load-Register command to the front-end chip. Since each front-end chip is addressed uniquely in a tracker, you can write different setting to individual front-end chip.

Calibration mask (64 bits)

Defines channel(s) into which a calibration strobe should be issued. If a channel is masked, no calibration charges will be injected on the channel. Each bit corresponds to a single input channel of the front-end chip.

Channel mask (64 bits)

Defines channel(s) on which a signal from a detector strip should be latched. If a channel is masked, no hit is recorded on the channel. Each bit corresponds to a single input channel of the front-end chip.

Trigger mask (64 bits)

Defines channel(s) which should contribute to a fast-OR signal of the chip. If a channel is masked, no signal on the channel generates a fast-OR signal. Each bit corresponds to a single input channel of the front-end chip.

Calibration DAC setting (7 bits)

Defines the amount of charges injected by a calibration strobe in combination of 6 bit DAC value and 1 bit range selection. Only one value can be set for a chip. Low range and high range are available for threshold DAC. Threshold voltage ranges from 0.3 fC to 19 fC (0.3 fC step) in low range and from 1.2 fC to 77 fC (1.2 fC step) in high range.

Threshold DAC setting (7 bits)

Defines threshold voltage in combination of 6 bit DAC value and 1 bit range selection. Only one threshold voltage can be set for a chip. Low range and high range are available for threshold DAC. Threshold voltage ranges from 6 mV to 380 mV (6 mV step) in low range and from 24 mV to 1.5 V (24 mV step) in high range.

Readout direction (1 bit)

Defines in which direction (left or right) the front-end chip should send out hit information.

A controller chip keeps following information in its control register of 8 bits in total. To set a set of parameters to the controller chip, a TEM board should send a Load-Register command to a controller chip. Since each controller chip is addressed uniquely in a tracker, you can write different setting to individual controller chip.

Readout mode (1 bit)

Defines whether the controller chip should initiate a readout sequence even without a fast-OR signal generated by the layer.

FCS attachment (1 bit)

Defines whether the controller chip should calculate an FCS (Frame Check Sequence) and attach it to data. An FCS is a bit pattern of 11 bits calculated from bit sequence of data being sent with a CRC algorithm. With FCS a receiver of the data can check whether the data is corrupted during transmission.

Number of chips (5 bit)

Defines the number of chips to be read by the controller chip.

Note that settings of readout direction of all the 25 front-end chips and two controller chips on an HDI must be consistent with each other. For example, suppose that you decide to readout the left 12 front-end chips from the left side of one HDI and the rest from the right. Then, you should set control direction of the left 12 front-end chips to “left”, that of the rest to “right”, and furthermore, you should set the number of chips of the left controller chip to “12” and that of the right one to “13”. If you set them otherwise, readout of the HDI may be screwed up.

4.3 Addressing Scheme

In each command sent to a controller chip, there is an address of a controller chip to communicate embedded. The address is called a controller chip address or a layer address. Some commands can be sent to a front-end chip through a controller chip. To do it, a TEM board sends a command to a controller chip to let it send a command to a front-end chip. In such a command, an address of the front-end chip must be included as well as a controller chip address. It is called a front-end address. And each of eight readout cables of the tracker is numbered from C0 to C7, each of which is connected a port 0 to 7 on a front panel of a TEM board.

A combination of three addresses specifies a single front-end chip in a tower: a front-end chip address, a layer address of the layer where the front-end chip belongs to, and a Kapton cable number of the cable which the layer connects to. A front-end chip address ranges 0 through 24 and is unique on an HDI; the left-most front-end chip on an HDI is addressed 0, the 2nd left-most chip 1, . . . , the right-most chip 24. A layer address, which is an address of controller chips on the layer, ranges from 0 to 7 and is unique on a Kapton cable (See Figure 2). Finally, A Kapton cable number ranges 0 through 7 and is unique on the tracker. The cable connecting left sides of HDI’s attached on +X side of the tracker is called C0, the one connecting right side of the HDI’s C1, and so on.

For a front-end chip address and a layer address, there is a broadcast address, which is 31 as a decimal number. For example, A controller chip accepts a command when an address in the command matches its own address or it is 31. The broadcast address is used to send a command to all the chips on the command bus.

Note that A front-end chip does not accepts a command from the right side controller chip when it is configured to be read out from the left side, and vice versa. This is true even for a command with a broadcast address. So, you should know readout direction of a front-end chip of interest, before you send a command to it, and choose an appropriate controller chip to send a command to. Only one

exception on the readout-direction rule is a Load-Register command; it is accepted by a front-end chip no matter which readout direction is set to the front-end chip and no matter which controller chip sends the command to it.

Special consideration should be made when a Load-GTFE-Register command is sent with a broadcast address. If a Load-GTFE-Register command is sent to a controller chip with a specific layer address and a broadcast front-end chip address, a control register of all the front-end chips on the specified layer will be overwritten. If a broadcast address is used both for a controller chip address and for a front-end chip address, all the front-end chips in the tracker will be re-written in one command.

5 Configuration

5.1 Controller and Cable Addresses

Table 3 shows for every read out cable the address of the last controller. It also lists the controller type that a cable reads.

Table 3. Last Controller Address, controller type.

Read-out Cable	Last Controller Address	Controller Type
0	7	R0
1	7	R1
2	7	R1
3	7	R0
4	6	R1
5	6	R0
6	5	R0
7	5	R1

The controller addresses on a cable are not consecutive any more because some trays were removed from the beam test tower. Table 4 shows the controller addresses. Position p0 is the closest to the bottom of the tracker. Cable zero to three read out seven controller whereas cable four to seven read only six controller.

Table 4. Controller Addresses for a cable

cable	p0	p1	p2	p3	p4	p5	p6
0,1	0	1	2	3	4	5	7
2,3	0	1	2	3	4	5	7
4,5	0	1	2	3	4	6	none
6,7	0	1	2	3	4	5	none

The table 5 shows the correspondence between tracker layer, read out cable and controller address. The index is random and was chosen to have even numbers for Y-layers and odd numbers for X-layers.

Table 5. Correspondence between tracker layer and cable/GTRC addresses.

Layer Index	View	R0 Controller		R1 Controller	
		cable	gtrc	cable	gtrc
0	Y	0	0	1	0
1	X	3	0	2	0
2	Y	5	0	4	0
3	X	6	0	7	0
4	Y	0	1	1	0
5	X	3	1	2	0
6	Y	5	1	4	0
7	X	6	1	7	0
8	Y	0	2	1	0
9	X	3	2	2	0
10	Y	5	2	4	0
11	X	6	2	7	0
12	Y	0	3	1	0
13	X	3	3	2	0
14	Y	5	3	4	0
15	X	6	3	7	0
16	Y	0	4	1	0
17	X	3	4	2	0
18	Y	5	4	4	0
19	X	6	4	7	0
20	Y	0	5	1	0
21	X	3	5	2	0
22	Y	5	6	4	0
23	X	6	5	7	0
24	Y	0	7	1	0
25	X	3	7	2	0

5.2 Known Problems

The front end chips (GTFE) and controller chips (GTRC) have to be configured before sensible data are read out. The purpose to configure the tracker is to ensure that all layers are read out, there is a valid fastOr signal for every layer and that noisy channels are masked from the trigger (or data if required).

The following list summarizes known problems for the eight read out cables.

Cable 0 : No problems.

Cable 1 : R1 controller type.

1. GTRC4: The fastOr is stuck high between GTFE 3 and 4. If these chips are read to cable 1 the fastOr will always be high. If only GTFE 5 - 24 are read to the controller the fastOr is good.
2. GTRC1: If read out there are always about 63 hits, mostly from GTFE 24. This means that data of this layer can't be read from this side but should be read from cable 0.

Cable 2 : No problems.

Cable 3 : No problems.

Cable 4 : R1 controller type.

1. GTRC2: The fastOr is stuck high between GTFE 23 and 24. In order to obtain a valid fastOr only GTFE 24 is allowed to be read.

Cable 5 : R0 controller type.

1. GTRC3: The fastOr is stuck high between GTFE 0 and GTRC. No valid fastOr is possible.

Cable 6 : No problems.

Cable 7 : No problems.

6 Testing

The two main tools to insure that the tracker is working properly are strip maps and cosmic trigger. Another possibility is to inject charges into the amplifier channels. However charge injection is more complex than simple wire maps and not discussed here.

6.1 Strip Maps

Strip maps show the occupancy for every channel for each tracker layer. Data are collected using random trigger or particle trigger. The main purpose of the strip maps is to find noisy and dead channels. Random trigger data are taken with different thresholds.

6.2 Cosmic Particles

Cosmic trigger are collected using the tracker self trigger or external scintillation counter. A single event display is needed to view the tracks. Cosmic tracks provide a rough estimation about the efficiency of the detectors.

7 Details on Tracker

This section describes details on the tracker for tracker experts' reference. It is not necessary to read this section, if you are not interested.

7.1 Control Register

A control register of a front-end chip consists of 207 bits, which are summarized in Table 6. When a control register is loaded with non-broadcast address, a front-end chip specified with the address outputs previous contents of the register on a CTRLREG output pad (single-ended CMOS signal), with bit 0 first in time. If it is loaded with a broadcast address, no signal is seen on the pad. The bit stream is received by a controller chip and forwarded to data output (DOUT). So far, a TEM board cannot capture nor store this bit stream. So a TEM board should keep track of control register contents of all the front-end chip in the tracker.

During loading a register, an HDI becomes very noisy. Especially, a fast-OR trigger bounces around, namely, many fake trigger signals will be seen on a fast-OR line (TOUT1-8). A TEM board should ignore these fake fast-OR's while it is loading control register settings.

Table 6. Control Register Contents of Front-end Chip

Bit ^{a)}	Contents	Remark
0-63	Calibration mask	Bit 0 for channel 0 and bit 63 for channel 63
64-127	Channel mask	Bit 64 for channel 63 and bit 127 for channel 0
128-191	Trigger mask	Bit 128 for channel 0 and bit 191 for channel 63
192-198	Calibration DAC	Bit 192 is the range select (1:high range, 0:low range) Bit 193 is MSB of DAC value and Bit 198 LSB Cal. charge $\approx (0.3 \times (\text{DACvalue} + 1))$ fC in low range Cal. charge $\approx (1.2 \times (\text{DACvalue} + 1))$ fC in high range
199-205	Threshold DAC	Bit 199 is the range select (1:high range, 0:low range) Bit 200 is MSB of DAC value and Bit 205 is LSB Threshold $\approx (6 \times (\text{DACvalue} + 1))$ mV in low range Threshold $\approx (24 \times (\text{DACvalue} + 1))$ mV in high range
206	Readout direction	1:right, 0:left

a) Bit 0 comes first in time.

A control register of a controller chip consists of 7 bits, 1 bit of which is not used and 6 of which are summarized in Table 7. When a control register is loaded with a specific address or a broadcast address, a controller chip specified with the address

outputs previous contents of the register on data output DOUT (differential CMOS signal), with bit 0 first in time. With a broadcast address only contents from the bottom layer will be seen at a TEM board. So far, a TEM board cannot capture nor store this bit stream. So a TEM board should keep track of control register contents of all the controller chip in the tracker.

Table 7. Control Register Contents of Controller Chip

Bit ^{a)}	Contents	Remark
0	Not used	
1	Readout mode	1:Readout the layer even if it didn't generate a fast-OR signal 0:Don't readout if it didn't
2	FCS ^{a)} attachment	1:Calculate 11 bit FCS and attach it at the end of data 0:No FCS calculated nor attached
3-7	Number of chips	Number of front-end chips to read from the side Bit 3 is MSB and bit 7 LSB.

a) Bit 0 comes first in time.

7.2 GTFE Command

Here is a complete list of commands for a front-end chip. See Table 8 for actual bit streams. Below are brief explanations on the commands.

Load control register Loads control register of the front-end chip.

Read event Starts the front-end chip shifting data out.

End read-event Stops the front-end chip shifting data out.

Clear event Clear one event in FIFO.

Calibration strobe Injects a test pulse into specified channel(s).

Reset chip Reset command decoders, control registers, and FIFO.

Reset FIFO Reset all the contents of FIFO.

7.3 GTRC Command

Here is a complete list of commands for a controller chip. See Table 8 for actual bit streams. Below are brief explanations on the commands. When a controller chip sends a command to front-end chips, it automatically supplies clock signals for front-end chips of an appropriate number of clock cycles depending on the command.

Load GTRC register Loads control register of the controller chip.

Read event Starts a readout sequence of an event; on receipt of this command, the controller chip sends a read event command to front-end chips with a broadcast address, supplies clocks to front-end chips to shift out data, reads in hit status being sent and store it to an event buffer, and sends an end-read-event command to front-end chips with a broadcast address.

Clear event Clears one event and sends a clear event command to front-end chips with a broadcast address if necessary

Load GTFE register Lets the controller chip send a load control register command to specified front-end chip(s)

Calibration strobe Lets the controller chip send a calibration-strobe command to specified front-end chip(s)

Turn on clock Force the controller chip to turn on clock output for front-end chips. Once a turn-on-clock command is sent to a controller chip, there is no way to stop the clock except for a reset-GTRC command, a reset pulse, and turning off the power.

Reset GTRC Resets control register and readout flags of the controller chips. Also, it stops an action in progress immediately if any.

Reset GTFE Lets the controller chip to send a reset-chip command to specified front-end chip(s).

Reset GTFE FIFO Lets the controller chip to send a reset-FIFO command to specified front-end chip(s).

7.4 Resetting Chips

There are a three ways to reset a front-end chip or a controller chip; by command, by a reset pulse, or by turning on power. The result of resetting varies depending on how it is reset as described below.

Table 8. Commands for a front-end chip GTFE64 and a controller chip GTRC

Chip	Command	Bit sequence (in time order)
GTFE	No-op	1 000 $f_0f_1f_2f_3f_4$
	Load control register	1 100 $f_0f_1f_2f_3f_4$ $d_0d_1 \cdots d_{206}$
	Read event	1 010 $f_0f_1f_2f_3f_4$
	Clear event	1 001 $f_0f_1f_2f_3f_4$
	Calibration strobe	1 110 $f_0f_1f_2f_3f_4$
	Reset chip	1 101 $f_0f_1f_2f_3f_4$
	Reset FIFO	1 011 $f_0f_1f_2f_3f_4$
	End read-event	1 111 $f_0f_1f_2f_3f_4$
GTRC	Load GTRC register	1 $a_4a_3a_2a_1a_0$ 000 $r_0r_1r_2r_3r_4r_5r_6r_7$
	Clear event	1 $a_4a_3a_2a_1a_0$ 001
	Read event	1 $a_4a_3a_2a_1a_0$ 010
	Load GTFE register	1 $a_4a_3a_2a_1a_0$ 011 1 100 $f_0f_1f_2f_3f_4$ $d_0d_1 \cdots d_{206}$
	Turn on clock	1 $a_4a_3a_2a_1a_0$ 100
	Calibration strobe	1 $a_4a_3a_2a_1a_0$ 101 1 110 $f_0f_1f_2f_3f_4$
	Reset GTFE	1 $a_4a_3a_2a_1a_0$ 110 1 101 $f_0f_1f_2f_3f_4$
	Reset GTFE FIFO	1 $a_4a_3a_2a_1a_0$ 110 1 011 $f_0f_1f_2f_3f_4$
Reset GTRC	1 $a_4a_3a_2a_1a_0$ 111	

a_i : i -th bit of a controller chip address. a_4 is MSB.

f_i : i -th bit of a front-end chip address. f_4 is MSB.

r_i : i -th bit of control register of a controller chip. r_0 is Bit 0 in Table 7.

d_i : i -th bit of control register of a front-end chip. d_0 is Bit 0 in Table 6

A reset pulse is a single-ended CMOS digital signal. There is a reset pad both on a front-end chip and on a controller chip, and they are connected on an HDI together. Also, they are connected to each other on a Kapton readout cable. Therefore, if you send a reset signal to one of the cables, you are resetting all the front-end chips and the controller chips connected on the cable.

Reset pulse A reset pulse resets a command decoder of the front-end chip. It does *not* change contents of control register. A reset pulse to a controller chip resets control register and readout flags of the controller chip. So, if you send a reset pulse to the tracker, you have to reconfigure controller chips but not front-end chips.

Reset-chip command to front-end chip A reset-chip command to a front-end chip resets a command decoder, a control register, and FIFO. Note, if you send a reset-chip command to front-end chips, you should reload control register of the front-end chips.

Reset-chip command to controller chip A reset-chip command to a controller chip resets readout flags, but *not* its control register. To maintain consistency between front-end chips and a controller chip, you should reset FIFO's of front-end chips also, when you send a reset-chip command to a controller chip.

Reset-FIFO command to front-end chip A reset-FIFO command resets a FIFO of specified front-end chip(s), namely, erases all the contents of the FIFO.

Power-on Reset Both a front-end chip and a controller chip has a power-on reset feature. It sets a default setting to a control register, clears a FIFO, resets a command decoder, and so on.

7.5 Readout Cable and Repeater Board

There are 8 Kapton readout cables attached to the tracker. Each of cable connects 8 HDI's facing on one side of the tracker to a repeater board attached to the tracker. Signals from the tracker is buffered at a repeater board and sent to a TEM board. Signals from a TEM board is not buffered. Repeater boards are powered by DVDD, or a digital power for an HDI.

A 37-pin Nanonics connector is mounted on the DAQ side of a Kapton cable and connects it to a repeater board. A Kapton cable has 8 "legs", each of which connects an HDI with a 25-pin Nanonics connector mounted on the leg. Pin-assignment of both connectors are in Tables 9 and 10.

Table 9. Signals on 37-pin Connector on Kapton Flexible Cable

Pin	Signal	
1	RESET	Reset pulse to HDI
2	AVDD2	2nd analog power supply
3	AGND	Analog ground
4	AVDD	Analog power supply
5	BIAS	Detector bias
6	TEMP1/1	Temperature sensor 1
7	TEMP1/2	
8	TEMP2/1	Temperature sensor 2
9	TEMP2/1	
10	TOUTP8	Fast-OR from 8th layer
11	TOUTN8	
12	TOUTP7	Fast-OR from 7th layer
13	TOUTN7	
14	TOUTP6	Fast-OR from 6th layer
15	TOUTN6	
16	TOUTP5	Fast-OR from 5th layer
17	TOUTN5	
18	TOUTP4	Fast-OR from 4th layer
19	TOUTN4	
20	TOUTP3	Fast-OR from 3rd layer
21	TOUTN3	
22	TOUTP2	Fast-OR from 2nd layer
23	TOUTN2	
24	TOUTP1	Fast-OR from 1st layer
25	TOUTN1	
26	TACKN	Trigger acknowledge to HDI
27	TACKP	
28	CLKN	Clock to HDI
29	CLKP	
30	CMDN	Command to HDI
31	CMDP	
32	DATIN	Data from HDI
33	DATIP	
34	TOKON	Token to HDI
35	TOKOP	
36	DGND	Digital ground
37	DVDD	Digital power supply

Table 10. Signals on 25-pin Connector on i -th leg of Kapton Flexible Cable

Pin	Signal	
1	RESET	Reset pulse to HDI
2	AVDD2	2nd analog power supply
3	AGND	Analog ground
4	AVDD	Analog power supply
5	BIAS	Detector bias
6	TEMP $_n/1$	Temperature sensor n (if assigned ^a)
7	TEMP $_n/2$	
8	TOUTP $_i$	Fast-OR to TEM
9	TOUTN $_i$	
10	TACKN	Trigger acknowledge from TEM (bus)
11	TACKP	
12	CLKN	Clock from TEM (bus)
13	CLKP	
14	CMDN	Command from TEM (bus)
15	CMDP	
16	DATIN	Data to the lower layer (daisy-chained)
17	DATIP	
18	DATIN	Data from the higher layer (daisy-chained)
19	DATIP	
20	TOKON	Token to the higher layer (daisy-chained)
21	TOKOP	
22	TOKON	Token from the lower layer (daisy-chained)
23	TOKOP	
24	DGND	Digital ground
25	DVDD	Digital power supply

a) A temperature sensor line is connected only on two legs of a Kapton cable. The location of the legs varies.